

RELIABILITY DATA  
LTM2884 New Substrate, Transformer, and Die Changes  
7/23/2019

• BIASED HIGHLY ACCELERATED STRESS TEST AT +130°C / 85%RH *					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	Equivalent K DEVICE HOURS AT +85°C**	NUMBER OF FAILURES
BGA 1515	100	1804	1812	192	0
Total	100			192	0
• UNBIASED HIGHLY ACCELERATED STRESS TEST AT +130°C / 85%RH *					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	Equivalent K DEVICE HOURS AT +85°C**	NUMBER OF FAILURES
BGA 1515	308	1804	1812	591.36	0
Total	308			591.36	0
• TEMPERATURE CYCLE TEST AT -55°C to +125°C *					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
BGA 1515	308	1804	1812	308	0
Total	308			308	0
• THERMAL SHOCK TEST AT -55°C to +125°C *					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	NUMBER OF FAILURES
BGA 1515	308	1804	1812	308	0
Total	308			308	0
• HIGH TEMPERATURE STORAGE LIFE TEST AT +150°C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HOURS	NUMBER OF FAILURES
BGA 1515	200	1804	1812	200	0
Total	200			200	0
• Electrical Test and CSAM post JEDEC MSL 3+ Preconditioning (216h at 30°C/60% R.H. plus 3x IR at 245°C)					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE		NUMBER OF FAILURES
BGA 1515	96	1804	1812		0
Total	96				0

\* Test is preceded by JEDEC Preconditioning: 192h 30°C/60% R.H. plus 3x IR at 245°C.

\*\* Assumes 20X acceleration from +85°C to +130°C